

Appl. No. 10/605,479  
Amdt. dated December 12, 2005  
Reply to Office action of November 15, 2005

### AMENDMENTS TO THE CLAIMS

1. (original) An electronic device comprising:
  - a primary circuit board;
  - 5 a secondary circuit board fixed on the primary circuit board; and
  - a plurality of metallic balls electrically connected between the primary circuit board and the secondary circuit board for transmitting signals between the primary circuit board and the secondary circuit board.
- 10 2. (original) The electronic device of claim 1 further comprising a thin layer of adhesive which is used for adhering the plurality of metallic balls to the secondary circuit board.
3. (original) The electronic device of claim 2 wherein the adhesive is a flux.
- 15 4. (original) The electronic device of claim 1 wherein the secondary circuit board is a circuit board with a communication module.
5. (original) The electronic device of claim 1 wherein the secondary circuit board
  - 20 comprises at least an electronic component for receiving and transmitting a first type of signal, at least an electronic component for receiving and transmitting a second type of signal, and a metallic frame for dividing the electronic component for receiving and transmitting the first type of signal and the electronic component for receiving and transmitting the second type of signal into different sides of the
  - 25 secondary circuit board.
6. (original) The electronic device of claim 5 wherein the first type of signal is a signal of a baseband circuit, and the second type of signal is a signal of an RF circuit.

Appl. No. 10/605,479

Amdt. dated December 12, 2005

Reply to Office action of November 15, 2005

- 5      7. (original) The electronic device of claim 5 wherein the metallic frame has a shape that comprises two substantially parallel line segments joined at corresponding ends by a line segment that is substantially perpendicular to the two parallel line segments.
8. (original) The electronic device of claim 5 wherein a protrusion is positioned on one side of the metallic frame.
- 10      9. (original) The electronic device of claim 5 further comprising a metallic shielding cap covering the secondary circuit board for shielding the plurality of electronic components of the secondary circuit board to prevent the plurality of electronic components from being interfered by electromagnetic radiation.
- 15      10. (original) The electronic device of claim 9 wherein a top of the metallic frame is capable of bonding with the metallic shielding cap when the metallic shielding cap covers the secondary circuit board.
- 20      11. (original) The electronic device of claim 1 wherein a plurality of electronic components is set on the secondary circuit board, and the electronic device further comprises a metallic shielding cap for shielding the plurality of electronic components of the secondary circuit board to prevent the plurality of electronic components from being interfered with by electromagnetic radiation.
- 25      12. (original) The electronic device of claim 1 wherein at least a metallic ball is used for a signal output of the secondary circuit board, and metallic balls adjacent to the signal output provide grounding.

Appl. No. 10/605,479  
Amdt. dated December 12, 2005  
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13. (original) The electronic device of claim 1 wherein the secondary circuit board is a printed circuit board.
14. (original) The electronic device of claim 1 wherein the metallic balls are made of an alloy of tin and lead.
15. (original) The electronic device of claim 1 wherein the metallic balls are made of an alloy of tin and lead having a ratio of tin to lead of 63:47.
16. (original) The electronic device of claim 1 wherein a number of the metallic balls is not less than 145.
- 17-26. (cancelled)